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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I²C, LINbus, UART/USART
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	42
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f10wlaafa-v0

Pin Count	Package	Data Flash	Fields of Application[Note]	Ordering Part Number
64 pins	64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)	Mounted	A	R5F10WLAAFA#30, R5F10WLAAFA#50, R5F10WLCAFA#30, R5F10WLCAFA#50, R5F10WLDAFA#30, R5F10WLDAFA#50, R5F10WLEAFA#30, R5F10WLEAFA#50, R5F10WLFAFA#30, R5F10WLFAFA#50, R5F10WLGAFA#30, R5F10WLGAFA#50
	64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)	Mounted	A G	R5F10WLAAFB#30, R5F10WLAAFB#50, R5F10WLCAFB#30, R5F10WLCAFB#50, R5F10WLDAFB#30, R5F10WLDAFB#50, R5F10WLEAFB#30, R5F10WLEAFB#50, R5F10WLFAFB#30, R5F10WLFAFB#50, R5F10WLGAFB#30, R5F10WLGAFB#50, R5F10WLAGFB#30, R5F10WLAGFB#50, R5F10WLCGFB#30, R5F10WLCGFB#50, R5F10WLDGFB#30, R5F10WLDGFB#50, R5F10WLEGFB#30, R5F10WLEGFB#50, R5F10WLFGFB#30, R5F10WLFGFB#50, R5F10WLGGFB#30, R5F10WLGGFB#50
80 pins	80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)	Mounted	A	R5F10WMAAFA#30, R5F10WMAAFA#50, R5F10WMCAFA#30, R5F10WMCAFA#50, R5F10WMDAFA#30, R5F10WMDAFA#50, R5F10WMEAFA#30, R5F10WMEAFA#50, R5F10WMFAFA#30, R5F10WMFAFA#50, R5F10WMGAFA#30, R5F10WMGAFA#50
	80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)	Mounted	A G	R5F10WMAAFB#30, R5F10WMAAFB#50, R5F10WMCAFB#30, R5F10WMCAFB#50, R5F10WMDAFB#30, R5F10WMDAFB#50, R5F10WMEAFB#30, R5F10WMEAFB#50, R5F10WMFAFB#30, R5F10WMFAFB#50, R5F10WMGAFB#30, R5F10WMGAFB#50, R5F10WMAGFB#30, R5F10WMAGFB#50, R5F10WMCGFB#30, R5F10WMCGFB#50, R5F10WMDGFB#30, R5F10WMDGFB#50, R5F10WMEGFB#30, R5F10WMEGFB#50, R5F10WMFGFB#30, R5F10WMFGFB#50, R5F10WMGGFB#30, R5F10WMGGFB#50

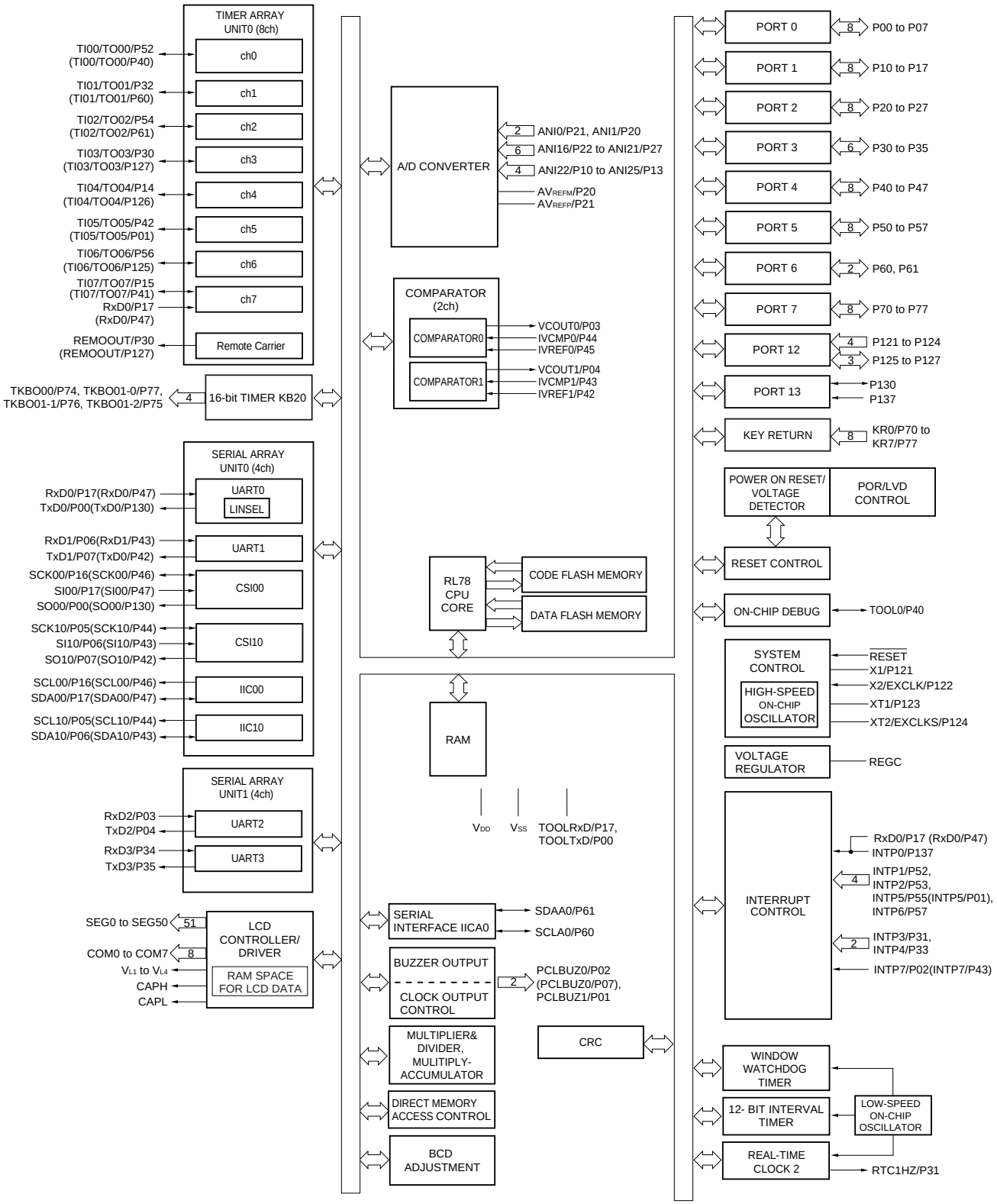
Note For the fields of application, see **Figure 1-1 Part Number, Memory Size, and Package of RL78/L13.**

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

1.4 Pin Identification

ANI0, ANI1, ANI16 to ANI25:	Analog Input
AV_{REFM}:	Analog Reference Voltage Minus
AV_{REFP}:	Analog Reference Voltage Plus
CAPH, CAPL:	Capacitor for LCD
COM0 to COM7:	LCD Common Output
EXCLK:	External Clock Input (Main System Clock)
EXCLKS:	External Clock Input (Subsystem Clock)
INTP0 to INTP7:	External Interrupt Input
IVCMP0, IVCMP1:	Comparator Input
IVREF0, IVREF1:	Comparator Reference Input
KR0 to KR7:	Key Return
P00 to P07:	Port 0
P10 to P17:	Port 1
P20 to P27:	Port 2
P30 to P35:	Port 3
P40 to P47:	Port 4
P50 to P57:	Port 5
P60, P61:	Port 6
P70 to P77:	Port 7
P121 to P127:	Port 12
P130, P137:	Port 13
PCLBUZ0, PCLBUZ1:	Programmable Clock Output/ Buzzer Output
REGC:	Regulator Capacitance
REMOOUT:	Remote control Output
$\overline{RESET}$:	Reset
RTC1HZ:	Real-time Clock 2 Correction Clock (1 Hz) Output
RxD0 to RxD3:	Receive Data
SCK00, SCK10, SCLA0:	Serial Clock Input/Output
SCL00, SCL10:	Serial Clock Output
SDAA0, SDA00, SDA10:	Serial Data Input/Output
SEG0 to SEG50:	LCD Segment Output
SI00, SI10:	Serial Data Input
SO00, SO10:	Serial Data Output
TI00 to TI07:	Timer Input
TO00 to TO07, TKBO00, TKBO01-0, TKBO01-1, TKBO01-2:	Timer Output
TOOL0:	Data Input/Output for Tool
TOOLRxD, TOOLTxD:	Data Input/Output for External Device
TxD0 to TxD3:	Transmit Data
VCOUT0, VCOUT1:	Comparator Output
V_{DD}:	Power Supply
V_{L1} to V_{L4}:	LCD Power Supply
V_{SS}:	Ground
X1, X2:	Crystal Oscillator (Main System Clock)
XT1, XT2:	Crystal Oscillator (Subsystem Clock)

1.5.2 80-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/L13 User's Manual.

(2/2)

Item		64-pin	80-pin
		R5F10WLx (x = A, C-G)	R5F10WMx (x = A, C-G)
Clock output/buzzer output controller		2	
		• 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f_{MAIN} = 20 MHz operation) • 256 Hz, 512 Hz, 1.024 kHz, 2.048 kHz, 4.096 kHz, 8.192 kHz, 16.384 kHz, 32.768 kHz (Subsystem clock: f_{SUB} = 32.768 kHz operation)	
8/10-bit resolution A/D converter		9 channels	12 channels
Comparator		2 channels	
Serial interface		[64-pin] • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I²C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I²C: 1 channel • UART: 1 channel [80-pin] • CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I²C: 1 channel • CSI: 1 channel/UART: 1 channel/simplified I²C: 1 channel • UART: 2 channels	
	I²C bus	1 channel	
LCD controller/driver		Internal voltage boosting method, capacitor split method, and external resistance division method are switchable.	
	Segment signal output	36 (32)[Note 1]	51 (47)[Note 1]
	Common signal output	4 (8)[Note 1]	
Multiplier and divider/multiply-accumulator		• 16 bits × 16 bits = 32 bits (Unsigned or signed) • 32 bits ÷ 32 bits = 32 bits (Unsigned) • 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed)	
DMA controller		4 channels	
Vectored interrupt sources	Internal	32	35
	External	11	11
Key interrupt		5	8
Reset		• Reset by $\overline{\text{RESET}}$ pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution[Note 2] • Internal reset by RAM parity error • Internal reset by illegal-memory access	
Power-on-reset circuit		• Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.)	
Voltage detector		• Rising edge: 1.67 V to 4.06 V (14 steps) • Falling edge: 1.63 V to 3.98 V (14 steps)	
On-chip debug function		Provided	
Power supply voltage		V_{DD} = 1.6 to 5.5 V (TA = -40 to +85°C) V_{DD} = 2.4 to 5.5 V (TA = -40 to +105°C)	
Operating ambient temperature		Consumer applications: T_A = –40 to +85°C Industrial applications: T_A = –40 to +105°C	

Notes 1. The values in parentheses are the number of signal outputs when 8 com is used.

2. This reset occurs when instruction code FFH is executed.
This reset does not occur during emulation using an in-circuit emulator or an on-chip debugging emulator.

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low[Note 1]	I_{OL1}	Per pin for P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130				20.0[Note 2]	mA
		Per pin for P60 and P61				15.0[Note 2]	mA
		Total of P40 to P47, P130 (When duty = 70%[Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			70.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			15.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			9.0	mA
			1.6 V ≤ V_{DD} < 1.8 V			4.5	mA
<R>		Total of P00 to P07, P10 to P17, P22 to P27, P30 to P35, P50 to P57, P70 to P77, P125 to P127 (When duty = 70%[Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			90.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			35.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			20.0	mA
			1.6 V ≤ V_{DD} < 1.8 V			10.0	mA
		Total of all pins (When duty = 70%[Note 3])				160.0	mA
	I_{OL2}	Per pin for P20 and P21				0.4[Note 2]	mA
		Total of all pins (When duty = 70%[Note 3])	1.6 V ≤ V_{DD} ≤ 5.5 V			0.8	mA

Notes 1. Value of the current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin

2. Do not exceed the total current value.

3. Output current value under conditions where the duty factor ≤ 70%.
The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)
  <Example> Where n = 80% and I_{OL} = 70.0 mA
  Total output current of pins = (70.0 × 0.7)/(80 × 0.01) ≅ 61.25 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (high-speed main) mode[Note 7]	f_{HOCO} = 48 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.71	1.95	mA
					V_{DD} = 3.0 V		0.71	1.95	
				f_{HOCO} = 24 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.49	1.64	mA
					V_{DD} = 3.0 V		0.49	1.64	
				f_{HOCO} = 16 MHz[Note 4], f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		0.43	1.11	mA
					V_{DD} = 3.0 V		0.43	1.11	
			LS (low-speed main) mode[Note 7]	f_{HOCO} = 8 MHz[Note 4], f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		280	770	μA
					V_{DD} = 2.0 V		280	770	
			LV (low-voltage main) mode[Note 7]	f_{HOCO} = 4 MHz[Note 4], f_{IH} = 4 MHz[Note 4]	V_{DD} = 3.0 V		430	700	μA
					V_{DD} = 2.0 V		430	700	
			HS (high-speed main) mode[Note 7]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.31	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.29	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.26	0.86	mA
					Resonator connection		0.45	1.15	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.25	0.86	mA
					Resonator connection		0.44	1.15	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.20	0.63	mA
					Resonator connection		0.28	0.71	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.19	0.63	mA
					Resonator connection		0.28	0.71	
			LS (low-speed main) mode[Note 7]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
				f_{MX} = 8 MHz[Note 3], V_{DD} = 2.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
			Subsystem clock operation	f_{SUB} = 32.768 kHz[Note 5], T_A = –40°C	Square wave input		0.34	0.62	μA
					Resonator connection		0.51	0.80	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +25°C	Square wave input		0.38	0.62	μA
					Resonator connection		0.57	0.80	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +50°C	Square wave input		0.46	2.30	μA
					Resonator connection		0.67	2.49	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +70°C	Square wave input		0.65	4.03	μA
					Resonator connection		0.91	4.22	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +85°C	Square wave input		1.00	8.04	μA
					Resonator connection		1.31	8.23	
	I_{DD3}[Note 6]	STOP mode[Note 8]	T_A = –40°C				0.18	0.52	μA
			T_A = +25°C				0.24	0.52	
			T_A = +50°C				0.33	2.21	
			T_A = +70°C				0.53	3.94	
			T_A = +85°C				0.93	7.95	

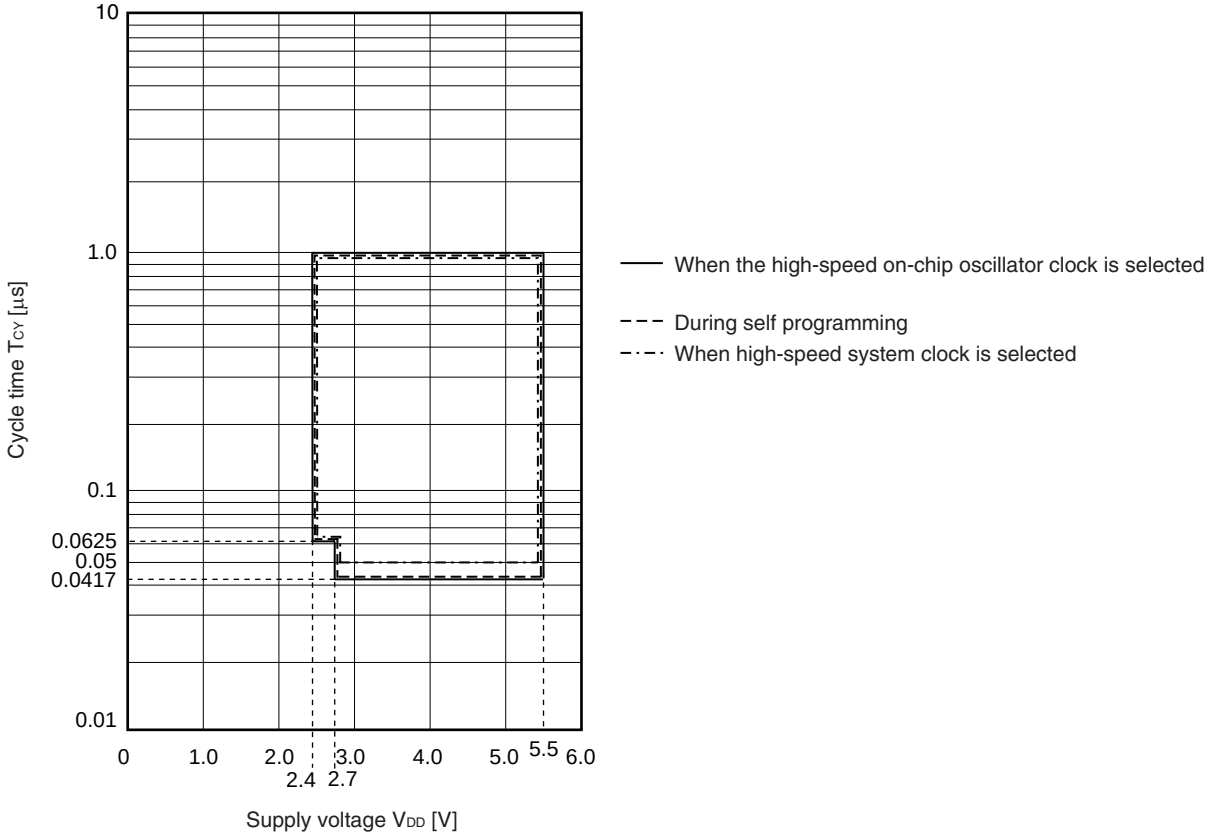
(**Notes** and **Remarks** are listed on the next page.)

Note Operation is not possible if 1.6 V ≤ V_{DD} < 1.8 V in LV (low-voltage main) mode while the system is operating on the subsystem clock.

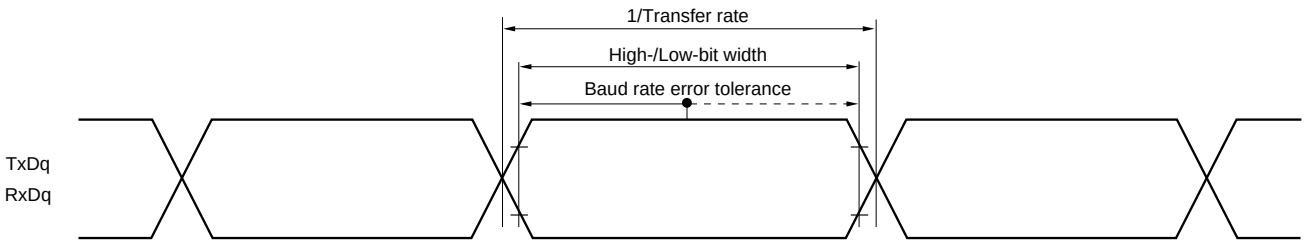
Remark f_{MCK}: Timer array unit operation clock frequency
(Operation clock to be set by the CKSmn0, CKSmn1 bits of timer mode register mn (TMRmn)
m: Unit number (m = 0), n: Channel number (n = 0 to 7))

Minimum Instruction Execution Time during Main System Clock Operation

T_{CY} vs V_{DD} (HS (high-speed main) mode)



UART mode bit width (during communication at same potential) (reference)



Remarks 1. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 3)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

(3) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (–) = AVREFM/ANI1 (ADREFM = 1), target pins: ANI0, ANI16 to ANI25

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{BGR}[Note 3],
Reference voltage (–) = AV_{REFM}[Note 4] = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES				8		bit
Conversion time	t_{CONV}	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error[Notes 1, 2]	E_{ZS}	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±0.60	%FSR
Integral linearity error[Note 1]	ILE	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±2.0	LSB
Differential linearity error[Note 1]	DLE	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±1.0	LSB
Analog input voltage	V_{AIN}			0		V_{BGR}[Note 3]	V

Notes 1. Excludes quantization error (±1/2 LSB).
2. This value is indicated as a ratio (%FSR) to the full-scale value.
3. See **2.6.2 Temperature sensor/internal reference voltage characteristics**.
4. When reference voltage (–) = V_{SS}, the MAX. values are as follows.
Zero-scale error: Add ±0.35%FSR to the AV_{REFM} MAX. value.
Integral linearity error: Add ±0.5 LSB to the AV_{REFM} MAX. value.
Differential linearity error: Add ±0.2 LSB to the AV_{REFM} MAX. value.

2.6.2 Temperature sensor /internal reference voltage characteristics

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V_{TMPS25}	ADS register = 80H, T_A = +25°C		1.05		V
Internal reference output voltage	V_{BGR}	ADS register = 81H	1.38	1.45	1.5	V
Temperature coefficient	F_{VTMPS}	Temperature sensor that depends on the temperature		–3.6		mV/°C
Operation stabilization wait time	t_{AMP}				5	μs

3.2 Oscillator Characteristics

3.2.1 X1 and XT1 oscillator characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f_X)Note	Ceramic resonator/ crystal resonator	2.7 V ≤ V_{DD} ≤ 5.5 V	1.0		20.0	MHz
		2.4 V ≤ V_{DD} < 2.7 V	1.0		16.0	
XT1 clock oscillation frequency (f_{XT})Note	Crystal resonator		32	32.768	35	kHz

Note Indicates only permissible oscillator frequency ranges. Refer to **AC Characteristics** for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark When using the X1 oscillator and XT1 oscillator, see **5.4 System Clock Oscillator** in the RL78/L13 User's Manual.

3.2.2 On-chip oscillator characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequencyNotes 1, 2	f_{IH}			1		24	MHz
High-speed on-chip oscillator clock frequency accuracy		+85 to +105°C	2.4 V ≤ V_{DD} ≤ 5.5 V	–2		+2	%
		–20 to +85°C	2.4 V ≤ V_{DD} ≤ 5.5 V	–1		+1	%
		–40 to –20°C	2.4 V ≤ V_{DD} ≤ 5.5 V	–1.5		+1.5	%
Low-speed on-chip oscillator clock frequency	f_{IL}				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				–15		+15	%

Notes 1. The high-speed on-chip oscillator frequency is selected by bits 0 to 4 of the option byte (000C2H/010C2H) and bits 0 to 2 of the HOCODIV register.

2. This indicates the oscillator characteristics only. Refer to **AC Characteristics** for the instruction execution time.

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low[Note 1]	I_{OL1}	Per pin for P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P70 to P77, P125 to P127, P130				8.5[Note 2]	mA
		Per pin for P60 and P61				15.0[Note 2]	mA
		Total of P40 to P47, P130 (When duty = 70%[Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			40.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			15.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			9.0	mA
		Total of P00 to P07, P10 to P17, P22 to P27, P30 to P35, P50 to P57, P70 to P77, P125 to P127 (When duty = 70%[Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			60.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			35.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			20.0	mA
		Total of all pins (When duty = 70%[Note 3])				100.0	mA
	I_{OL2}	Per pin for P20 and P21				0.4[Note 2]	mA
		Total of all pins (When duty = 70%[Note 3])	2.4 V ≤ V_{DD} ≤ 5.5 V			0.8	mA

Notes 1. Value of the current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin

2. Do not exceed the total current value.

3. Output current value under conditions where the duty factor ≤ 70%.
The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OL} = 40.0 mA

Total output current of pins = (40.0 × 0.7)/(80 × 0.01) = 35.0 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

Notes 1. Current flowing to V_{DD}.

2. When high speed on-chip oscillator and high-speed system clock are stopped.

3. Current flowing only to the real-time clock 2 (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The value of the current for the RL78 microcontrollers is the sum of the values of either I_{DD1} or I_{DD2}, and I_{RTC}, when the real-time clock 2 operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, I_{FIL} should be added. I_{DD2} subsystem clock operation includes the operational current of real-time clock 2.

4. Current flowing only to the 12-bit interval timer (excluding the operating current of the low-speed on-chip oscillator and the XT1 oscillator). The value of the current for the RL78 microcontrollers is the sum of the values of either I_{DD1} or I_{DD2}, and I_{TMKA}, when the 12-bit interval timer operates in operation mode or HALT mode. When the low-speed on-chip oscillator is selected, I_{FIL} should be added.

5. Current flowing only to the watchdog timer (including the operating current of the low-speed on-chip oscillator). The current value of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{WDT} when the watchdog timer operates.

6. Current flowing only to the A/D converter. The current value of the RL78 microcontrollers is the sum of I_{DD1} or I_{DD2} and I_{ADC} when the A/D converter operates in an operation mode or the HALT mode.

7. Current flowing only to the LVD circuit. The current value of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{LVD} when the LVD circuit operates.

8. Current flowing only during data flash rewrite.

9. Current flowing only during self programming.

10. For shift time to the SNOOZE mode, see **21.3.3 SNOOZE mode** in the RL78/L13 User's Manual.

11. Current flowing only to the comparator circuit. The current value of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{CMP} when the comparator circuit operates.

12. Current flowing only to the LCD controller/driver. The value of the current for the RL78 microcontrollers is the sum of the supply current (I_{DD1} or I_{DD2}) and LCD operating current (I_{LCD1}, I_{LCD2}, or I_{LCD3}), when the LCD controller/driver operates in operation mode or HALT mode. However, not including the current flowing into the LCD panel. Conditions of the TYP. value and MAX. value are as follows.

- Setting 20 pins as the segment function and blinking all
- Selecting f_{SUB} for system clock when LCD clock = 128 Hz (LCDC0 = 07H)
- Setting four time slices and 1/3 bias

13. Not including the current flowing into the external division resistor when using the external resistance division method.

Remarks 1. f_{IL}: Low-speed on-chip oscillator clock frequency

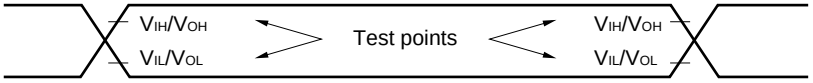
2. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

3. f_{CLK}: CPU/peripheral hardware clock frequency

4. The temperature condition for the TYP. value is T_A = 25°C.

3.5 Peripheral Functions Characteristics

AC Timing Test Points



3.5.1 Serial array unit

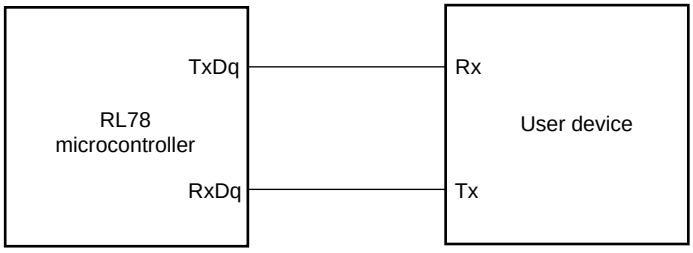
(1) During communication at same potential (UART mode)
(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Transfer rate[Note]				f_{MCK}/12	bps
		Theoretical value of the maximum transfer rate f_{CLK} = 24 MHz, f_{MCK} = f_{CLK}		2.0	Mbps

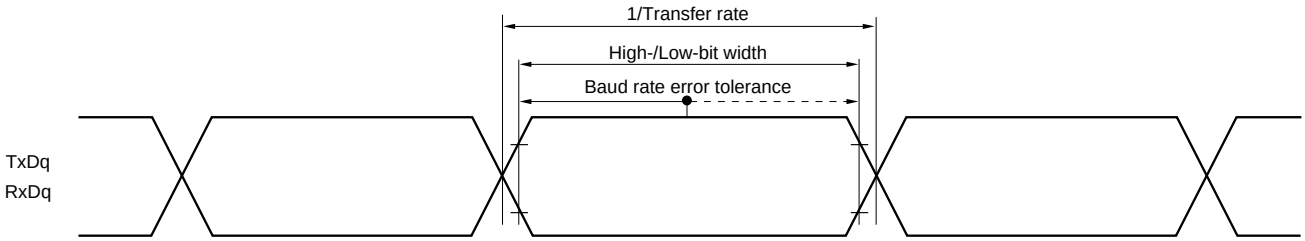
Note Transfer rate in the SNOOZE mode is 4800 bps only.

Caution Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg).

UART mode connection diagram (during communication at same potential)



UART mode bit width (during communication at same potential) (reference)



Remarks 1. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 3)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

(5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2)
(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

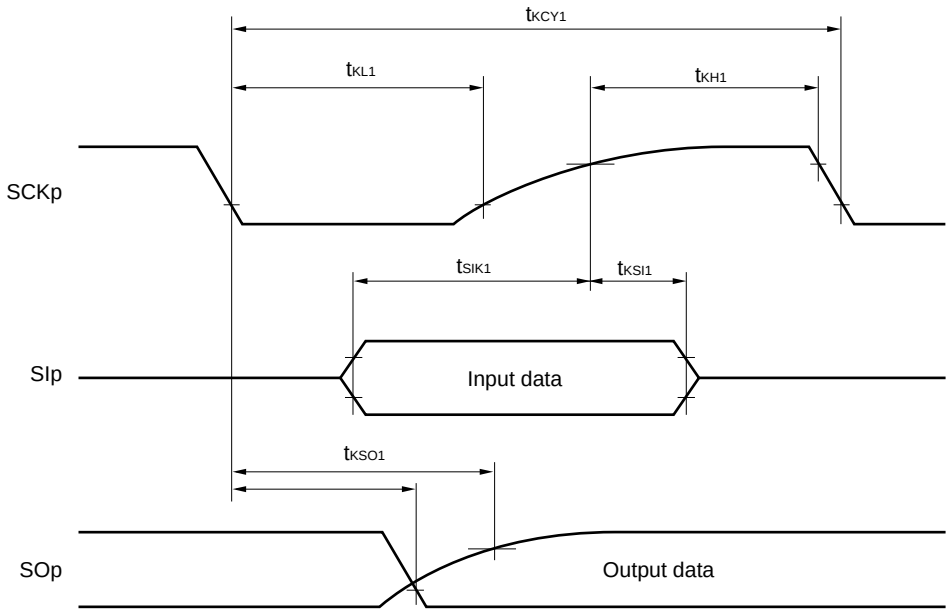
Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
Transfer rate		Reception	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		$f_{MCK}/12$ Note	bps
			Theoretical value of the maximum transfer rate f_{CLK} = 24 MHz, f_{MCK} = f_{CLK}		2.0	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		$f_{MCK}/12$ Note	bps
			Theoretical value of the maximum transfer rate f_{CLK} = 24 MHz, f_{MCK} = f_{CLK}		2.0	Mbps
			2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		$f_{MCK}/12$ Note	bps
			Theoretical value of the maximum transfer rate f_{CLK} = 24 MHz, f_{MCK} = f_{CLK}		2.0	Mbps

Note Transfer rate in SNOOZE mode is 4800 bps only.

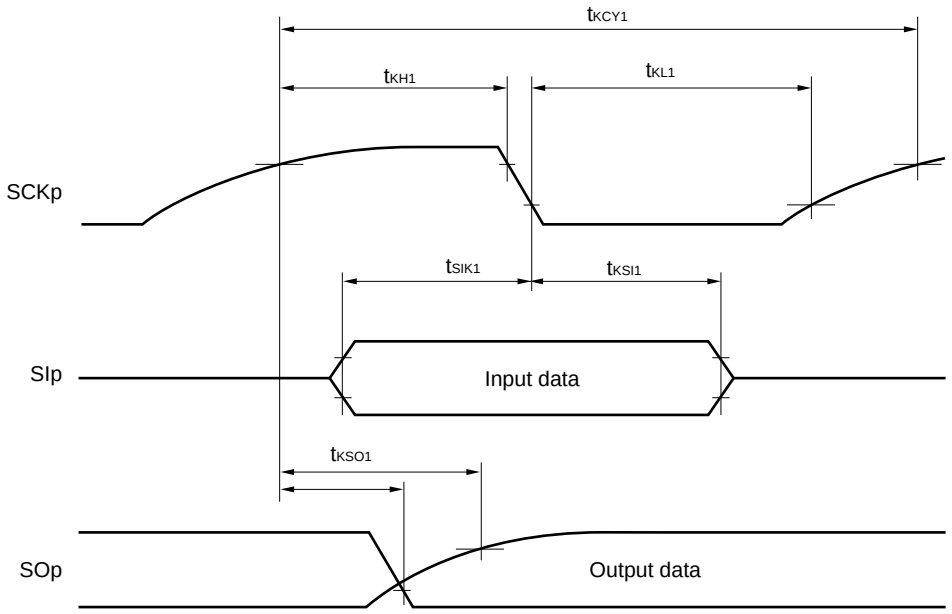
Caution **Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg).** For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

Remarks 1. V_b[V]: Communication line voltage
2. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 3)
3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 10), m: Unit number, n: Channel number (mn = 00, 02),
g: PIM and POM number (g = 0, 1)